Chiplet Summit Announces its Pre-Conference Day Schedule

SAN DIEGO, CA – December 10, 2024 — Emphasis is on bringing diverse practitioners up to date on all aspects of chiplets. The third annual Chiplet Summit, to occur on January 21-23 at the Santa Clara Convention Center, has now set its pre-conference day schedule for Tuesday, January 21.

Tutorial subjects are:

Morning (8:30 am-noon):

- Chiplet Basics
- Advanced Packaging Methods
- Introduction to Die-to-Die Interfaces (sponsored by Alphawave Semi)

Afternoon (1:00-5:00 pm):

- Design Methods
- Working with Foundries
- Applying Die-to-Die Interfaces (sponsored by the UCIe Consortium)
- Open Chiplet Economy (sponsored by Open Compute Project)

Special coverage includes new versions of UCIe and BoW, plus current CEA research on distributed large-scale AI systems using co-packaged optics and silicon photonics. The OCP tutorial reports on the open chiplet economy in which designers simply plug in chiplets they get from a marketplace.

Other features are a Superpanel on Chiplets - The Key to Solving the AI Energy Gap and the popular expert table session featuring one-on-one interaction with experts on key subjects and issues.

Summit General Chair Chuck Sobey says, “At our pre-conference day, attendees focused on design, packaging, test, or integration can catch up on advances in other areas. Meanwhile, beginners can learn the basics of all the diverse tasks. Everyone can profit from our superpanel on AI and ask their questions at our expert table session.”

To discuss exhibiting, contact:

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About Chiplet Summit

Chiplet Summit, a product of Semper Technologies, showcases the emerging chiplet market.

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